stacked on each of the top surface and the bottom surface of the probe holder 3B; the holder member 4 that is provided around the probe holder 3B, and that suppresses a displacement of the semiconductor integrated circuit 100 being brought into contact with the signal probes 2 and the first grounding probe 5 during a test; and a connection pipe 9A that is electrically connected to the first grounding probe 5 via the connecting member 8A.

[0080] The connecting member 8A has a main body 81a made of an insulating material such as resin, machinable ceramic, or silicone, the first conductive portion 82 that is conductive, that forms a part of a surface of the connecting member 8A, together with a surface of the main body 81a, and that is brought into contact with the connection pipe 9 (the conductive pipe 92 described later), and a second conductive portion 83a that is conductive, that extends from the first conductive portion 82, that forms a part of a surface of the connecting member 8A, together with a surface of the main body 81a, and that is brought into contact with the first grounding probe 5. To the connecting member 8A, holder holes 84 for housing the signal probes 2 are provided in the same number as the number of the holder holes 37B, 38B.

[0081] The connection pipe 9A includes a tubular insulating pipe 91A through which the signal probe 2 is passed, and the conductive pipe 92 provided on the outer circumference of the insulating pipe 91A.

[0082] The insulating pipe 91A is made of an insulating material such as fluorine-based resin (e.g., polytetrafluoroethylene). The insulating pipe 91A is provided with a holder hole 93A for housing the signal probe 2. The holder hole 93A for housing the signal probe 2 has a hole shape having a uniform diameter in the